

# ABSTRACT OF THE DISCLOSURE

[0032] A method of fabricating a thermal conductive plug of a ceramic substrate of a multi-chip package. A plurality of conductive openings and thermal conductive openings are formed on green tapes. A metal paste is filled into the conductive openings and the thermal conductive openings. The green tapes are stacked together so that the metal paste inside the conductive openings and the thermal conductive openings of every green tape is in contact respectively with its neighboring metal paste within the conductive openings and thermal conductive openings of the green tapes. Cofire those green tapes and the metal paste to form a pre-substrate. The pre-substrate comprises an insulating structure, a plurality of thermal conductive plugs and conductive plugs.

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